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**INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT**

Application Number: 10/055,560  
 Filing Date: January 22, 2002  
 First Named Inventor: Mou-Shiung Lin  
 Art Unit: 2813  
 Examiner Name: James M. Mitchell

(Use as many sheets as necessary)

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Attorney Docket No: 085027-0058

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EXAMINER

DATE CONSIDERED